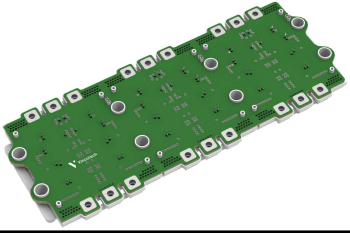
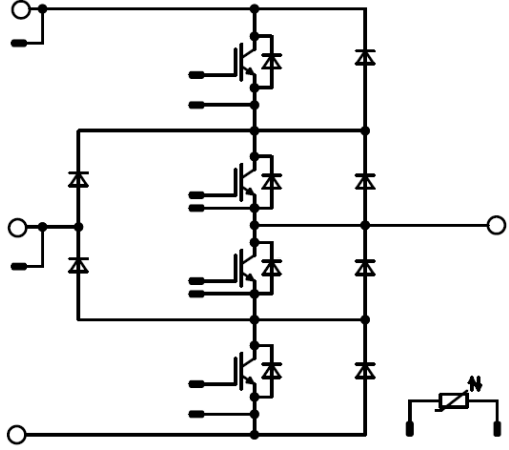




Vincotech

VINcoNPC X12	1500 V / 1200 A
<div style="background-color: #eee; padding: 2px; margin-bottom: 5px;">Features</div> <ul style="list-style-type: none"> Low inductive package Enables four-quadrant operation High efficiency 	<div style="background-color: #eee; padding: 2px; margin-bottom: 5px;">VINco X12 housing</div> 
<div style="background-color: #eee; padding: 2px; margin-bottom: 5px;">Target applications</div> <ul style="list-style-type: none"> Solar Inverters UPS 	<div style="background-color: #eee; padding: 2px; margin-bottom: 5px;">Schematic</div> 
<div style="background-color: #eee; padding: 2px; margin-bottom: 5px;">Types</div> <ul style="list-style-type: none"> 70-W624NIA1K2M702-L400FP70 	

Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Buck Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current	I_C	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	1270	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	2400	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	2375	W
Gate-emitter voltage	V_{GES}		±20	V
Maximum junction temperature	T_{jmax}		175	°C



Vincotech

Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Buck Diode				
Peak repetitive reverse voltage	V_{RRM}		1200	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	826	A
Repetitive peak forward current	I_{FRM}		2400	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	1358	W
Maximum junction temperature	T_{jmax}		175	°C
Buck Sw. Protection Diode				
Peak repetitive reverse voltage	V_{RRM}		1200	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	104	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	270	W
Maximum junction temperature	T_{jmax}		175	°C
Boost Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current	I_C	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	1270	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	2400	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	2375	W
Gate-emitter voltage	V_{GES}		±20	V
Maximum junction temperature	T_{jmax}		175	°C
Boost Diode				
Peak repetitive reverse voltage	V_{RRM}		1200	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	826	A
Repetitive peak forward current	I_{FRM}		2400	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	1358	W
Maximum junction temperature	T_{jmax}		175	°C



Vincotech

Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Boost Sw.Inv.Diode				
Peak repetitive reverse voltage	V_{RRM}		1200	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	826	A
Repetitive peak forward current	I_{FRM}		2400	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	1358	W
Maximum junction temperature	T_{jmax}		175	°C

Boost Sw. Protection Diode

Peak repetitive reverse voltage	V_{RRM}		1200	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	104	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	270	W
Maximum junction temperature	T_{jmax}		175	°C

Module Properties

Thermal Properties

Storage temperature	T_{stg}		-40...+125	°C
Operation temperature under switching condition	T_{jop}		-40...(T _{jmax} - 25)	°C
Maximum allowed PCB temperature	T_{PCB}		125	°C

Isolation Properties

Isolation voltage	V_{isol}	DC Test Voltage* $t_p = 2\text{ s}$	4000	V
		AC Voltage $t_p = 1\text{ min}$	2500	V
Creepage distance			min. 12,7	mm
Clearance			min. 12,7	mm
Comparative Tracking Index	CTI		> 200	

*100 % tested in production



Vincotech

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
		V_{GS} [V]	V_{GE} [V]	V_{DS} [V]	I_D [A]	T_j [°C]	Min	Typ	Max	

Buck Switch

Static

Parameter	Symbol	$V_{GE} = V_{CE}$	V_{GS} [V]	V_{CE} [V]	I_D [A]	T_j [°C]	Min	Typ	Max	Unit
Gate-emitter threshold voltage	$V_{GE(th)}$				0,12	25	5,4	6	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		1200	25 125 150		1,53 1,70 1,75	2,05	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			1320	μA
Gate-emitter leakage current	I_{GES}		20	0		25			6	μA
Internal gate resistance	r_g							none		Ω
Input capacitance	C_{ies}							252		nF
Output capacitance	C_{oes}		0	10		25		8,4		
Reverse transfer capacitance	C_{res}							3,36		
Gate charge	Q_g		15	600	1200	25		7800		nC

Thermal

Parameter	Symbol	Material	Min	Typ	Max	Unit
Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material $\lambda = 3,4$ W/mK				0,040 K/W

Dynamic

Parameter	Symbol	$R_{goff} = 0,417 \Omega$ $R_{gon} = 0,417 \Omega$	V_{GS} [V]	V_{CE} [V]	I_D [A]	T_j [°C]	Min	Typ	Max	Unit
Turn-on delay time	$t_{d(on)}$		16/-8	600	1190	25 125 150		166		ns
Rise time	t_r						25 125 150	42 45 47		
Turn-off delay time	$t_{d(off)}$						25 125 150	217 249 257		
Fall time	t_f						25 125 150	74 85 101		
Turn-on energy (per pulse)	E_{on}						25 125 150	88 110 117	mWs	
Turn-off energy (per pulse)	E_{off}	25 125 150	77 108 117							



Vincotech

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
		V_{GE} [V]	V_{CE} [V]	I_C [A]	T_j [°C]	Min	Typ	Max		

Buck Diode

Static

Forward voltage	V_F				1200	25 125		1,82 1,96	2,1	V
Reverse leakage current	I_R			1200		25			720	μA

Thermal

Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material $\lambda = 3,4$ W/mK						0,07		K/W
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Dynamic

Peak recovery current	I_{RRM}					25 125 150		1081 1228 1262		A
Reverse recovery time	t_{rr}					25 125 150		270 408 431		ns
Recovered charge	Q_r	$di/dt = 20584$ A/μs $di/dt = 24636$ A/μs $di/dt = 23099$ A/μs	16/-8	600	1190	25 125 150		122 194 207		μC
Reverse recovered energy	E_{rec}					25 125 150		42,0 73,7 78,2		mWs
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					25 125 150		13899 12695 12576		A/μs

Buck Sw. Protection Diode

Static

Forward voltage	V_F				90	25		2,38	2,71	V
Reverse leakage current	I_R			1200		25 150			0,36 10,8	mA

Thermal

Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material $\lambda = 3,4$ W/mK						0,35		K/W
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Vincotech

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
		V_{GS} [V]	V_{GE} [V]	V_{DS} [V]	I_C [A]	T_j [°C]	Min	Typ	Max	

Boost Switch

Static

Parameter	Symbol	$V_{GE} = V_{CE}$	V_{GS} [V]	V_{DS} [V]	I_C [A]	T_j [°C]	Min	Typ	Max	Unit
Gate-emitter threshold voltage	$V_{GE(th)}$				0,12	25	5,4	6	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		1200	25 125 150		1,53 1,70 1,75	2,05	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			1320	μA
Gate-emitter leakage current	I_{GES}		20	0		25			6	μA
Internal gate resistance	r_g							none		Ω
Input capacitance	C_{ies}							252		nF
Output capacitance	C_{oes}		0	10		25		8,4		
Reverse transfer capacitance	C_{res}							3,36		
Gate charge	Q_g		15	600	1200	25		7800		nC

Thermal

Parameter	Symbol	Material	Min	Typ	Max	Unit
Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material $\lambda = 3,4$ W/mK				0,040 K/W

Dynamic

Parameter	Symbol	R_{goff}	R_{gon}	I_C [A]	T_j [°C]	Min	Typ	Max	Unit
Turn-on delay time	$t_{d(on)}$	$R_{goff} = 0,417 \Omega$ $R_{gon} = 0,417 \Omega$	16/-8	600	1179	25	163		ns
Rise time	t_r					125	156		
Turn-off delay time	$t_{d(off)}$					150	157		
Fall time	t_f					25	44		
Turn-on energy (per pulse)	E_{on}					25	85		mWs
Turn-off energy (per pulse)	E_{off}					125	98		
						150	104		
						25	76		
						125	107		
						150	114		



Vincotech

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
		V_{GE} [V]	V_{CE} [V]	I_C [A]	T_j [°C]	Min	Typ	Max		

Boost Diode

Static

Forward voltage	V_F				1200	25 125		1,82 1,96	2,1	V
Reverse leakage current	I_R				1200	25			720	μA

Thermal

Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material $\lambda = 3,4$ W/mK						0,07		K/W
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Dynamic

Peak recovery current	I_{RRM}					25 125 150		951 1173 1199		A
Reverse recovery time	t_{rr}					25 125 150		286 413 452		ns
Recovered charge	Q_r	$di/dt = 21875$ A/μs $di/dt = 26999$ A/μs $di/dt = 25438$ A/μs	16/-8	600	1179	25 125 150		119 192 216		μC
Reverse recovered energy	E_{rec}					25 125 150		41 72 82		mWs
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					25 125 150		7710 8389 8083		A/μs

Boost Sw.Inv.Diode

Static

Forward voltage	V_F				1200	25 125		1,82 1,96	2,1	V
Reverse leakage current	I_R				1200	25			720	μA

Thermal

Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material $\lambda = 3,4$ W/mK						0,07		K/W
-------------------------------------	---------------	---	--	--	--	--	--	------	--	-----



Vincotech

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
		V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V]	I_C [A] I_D [A]	I_F [A]	T_j [°C]	Min	Typ	Max	

Boost Sw. Protection Diode

Static

Forward voltage	V_F				90	25		2,38	2,71	V
Reverse leakage current	I_R			1200		25 150			0,36 10,8	mA

Thermal

Thermal resistance junction to sink	$R_{th(j-s)}$	phase-change material $\lambda = 3,4$ W/mK						0,35		K/W
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Thermistor

Rated resistance	R					25		22		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	$R_{100} = 1484 \Omega$				100	-5		5	%
Power dissipation	P					25		5		mW
Power dissipation constant						25		1,5		mW/K
B-value	$B_{(25/50)}$	Tol. ± 1 %				25		3962		K
B-value	$B_{(25/100)}$	Tol. ± 1 %				25		4000		K
Vincotech NTC Reference									I	

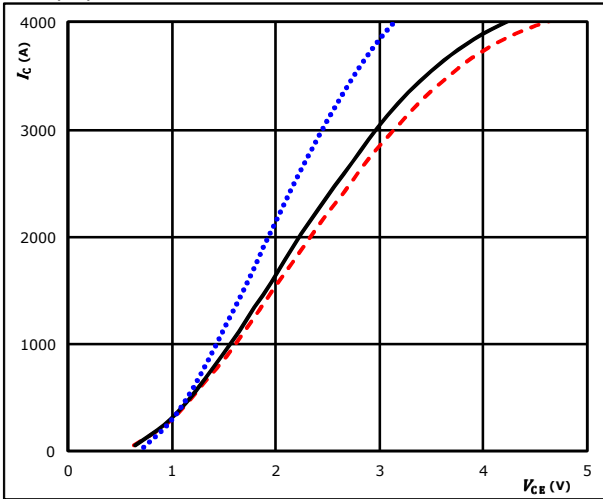


Buck Switch Characteristics

figure 1. IGBT

Typical output characteristics

$I_C = f(V_{CE})$

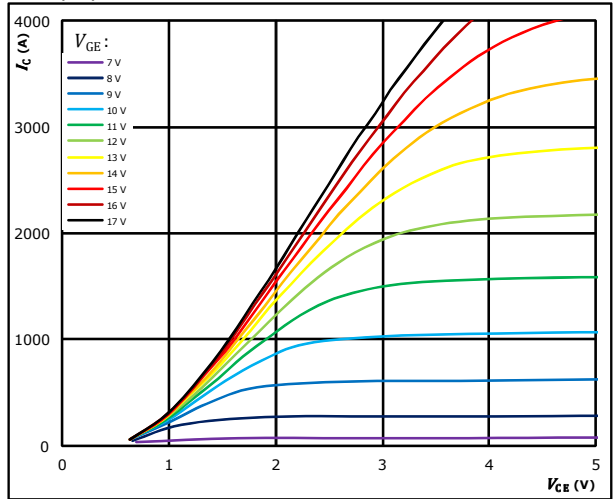


$t_p = 250 \mu s$
 $V_{GE} = 15 V$
 $T_j: 25 \text{ }^\circ C$ (blue dotted line)
 $125 \text{ }^\circ C$ (black solid line)
 $150 \text{ }^\circ C$ (red dashed line)

figure 2. IGBT

Typical output characteristics

$I_C = f(V_{CE})$

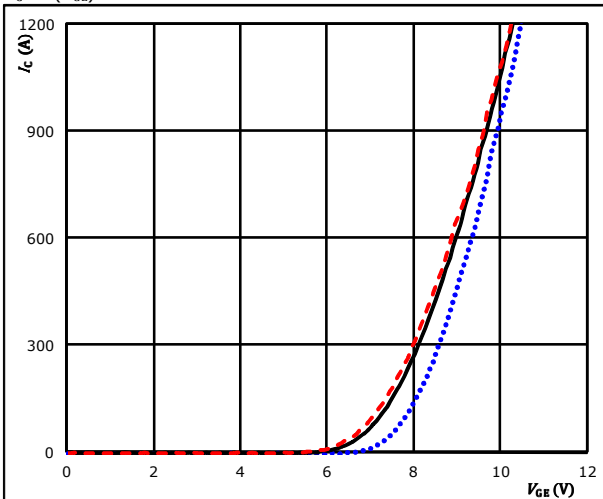


$t_p = 250 \mu s$
 $T_j = 150 \text{ }^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. IGBT

Typical transfer characteristics

$I_C = f(V_{GE})$

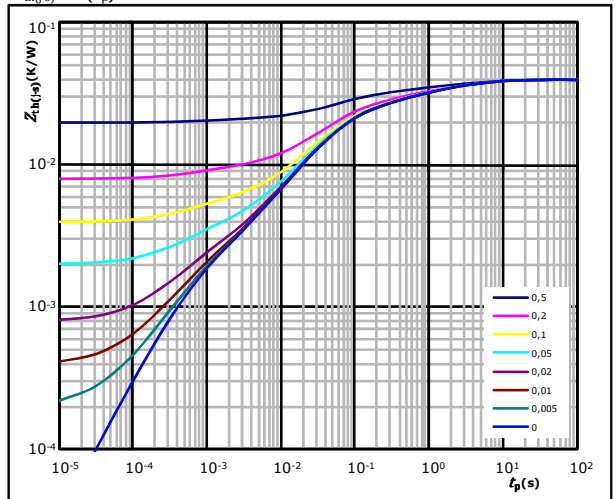


$t_p = 100 \mu s$
 $V_{CE} = 10 V$
 $T_j: 25 \text{ }^\circ C$ (blue dotted line)
 $125 \text{ }^\circ C$ (black solid line)
 $150 \text{ }^\circ C$ (red dashed line)

figure 4. IGBT

Transient thermal impedance as function of pulse duration

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$
 $R_{th(j-s)} = 0,040 \text{ K/W}$
 IGBT thermal model values

R (K/W)	τ (s)
4,77E-03	9,47E-01
7,48E-03	2,04E-01
7,36E-03	3,92E-02
1,45E-02	8,36E-03
3,81E-03	2,61E-03
8,43E-04	3,68E-04
1,21E-03	8,72E-05

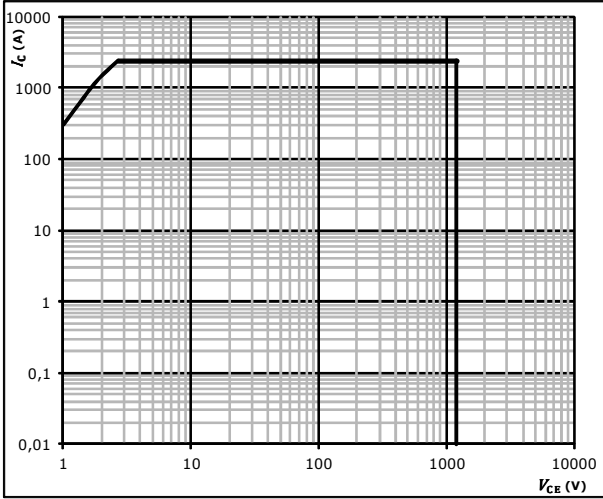


Buck Switch Characteristics

figure 5. IGBT

Safe operating area

$$I_C = f(V_{CE})$$



- D = single pulse
- T_s = 80 °C
- V_{GE} = ±15 V
- T_j = T_{jmax}

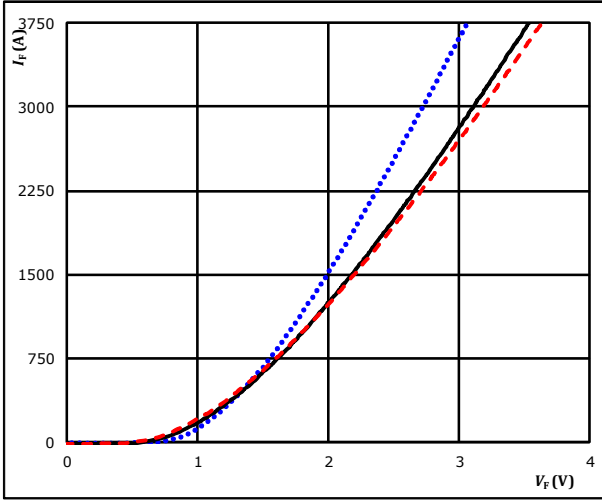


Buck Diode Characteristics

figure 1. FWD

Typical forward characteristics

$$I_F = f(V_F)$$

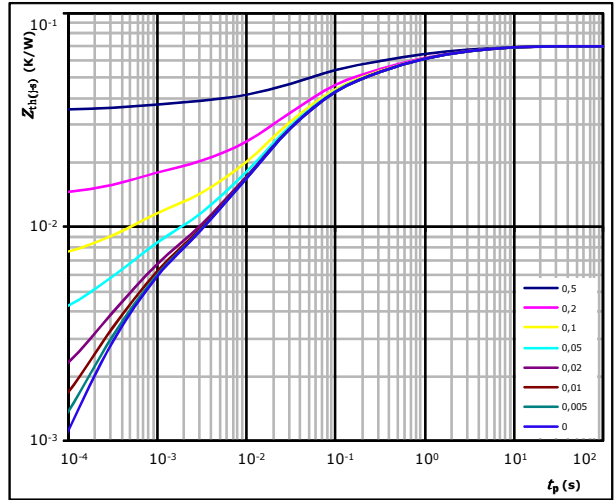


$t_p = 250 \mu s$
 T_j : 25 °C
 125 °C ———
 150 °C - - - -

figure 2. FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 0,07 \text{ K/W}$

FWD thermal model values

R (K/W)	τ (s)
4,91E-03	1,04E+00
1,02E-02	2,14E-01
1,57E-02	4,54E-02
2,42E-02	7,86E-03
8,72E-03	2,17E-03
2,15E-03	3,47E-04
4,02E-03	7,64E-05

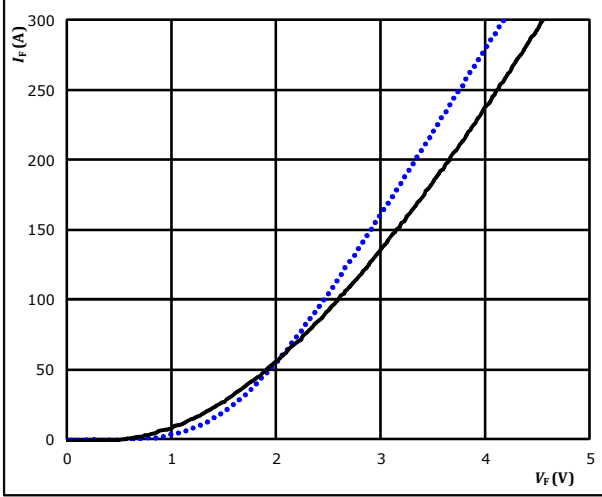


Buck Sw. Protection Diode Characteristics

figure 1. FWD

Typical forward characteristics

$$I_F = f(V_F)$$

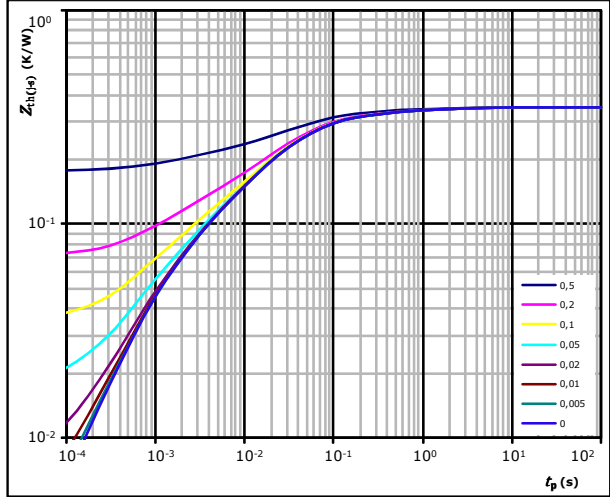


$t_p = 250 \mu s$ $T_j: 25 \text{ }^\circ\text{C}$ (dotted blue line) $125 \text{ }^\circ\text{C}$ (solid black line)

figure 2. FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 0,35 \text{ K/W}$

FWD thermal model values

R (K/W)	τ (s)
1,68E-02	5,53E-01
3,42E-02	7,61E-02
1,32E-01	1,28E-02
9,39E-02	3,66E-03
3,70E-02	9,02E-04
3,86E-02	2,43E-04



Boost Switch Characteristics

figure 1. IGBT

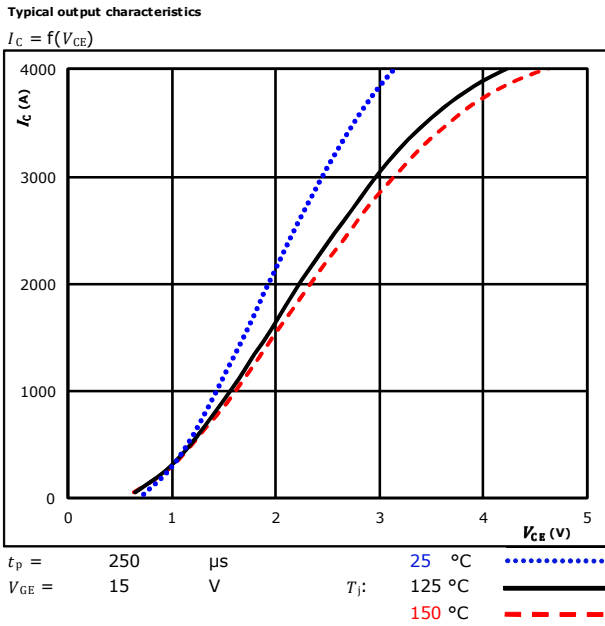


figure 2. IGBT

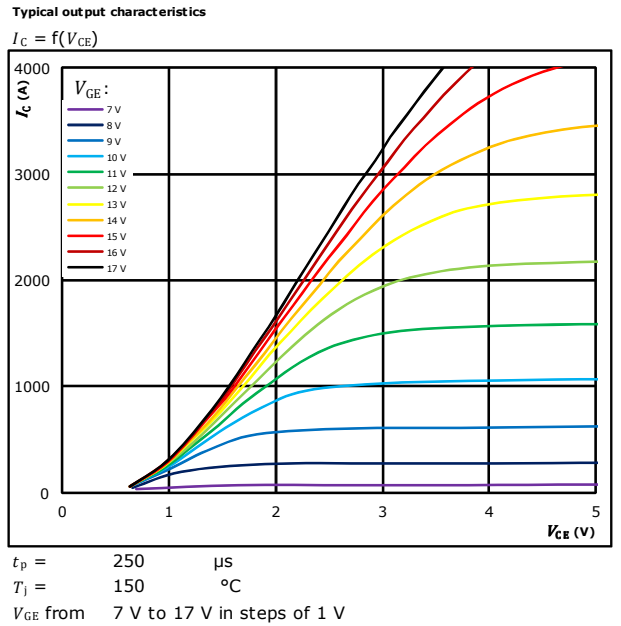


figure 3. IGBT

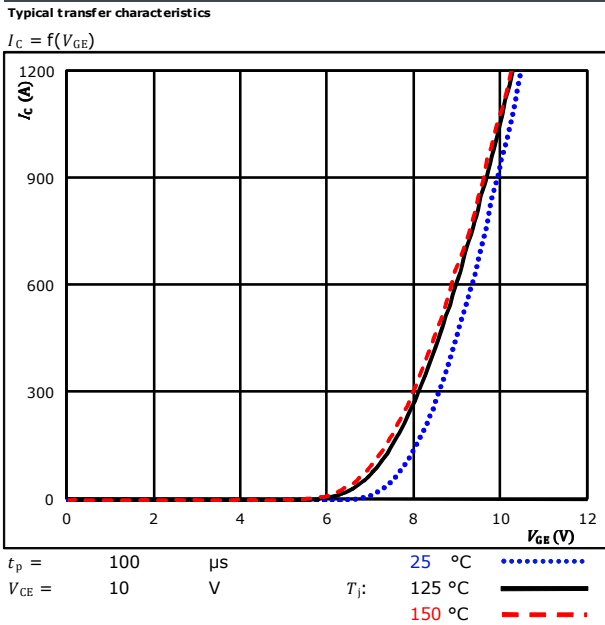
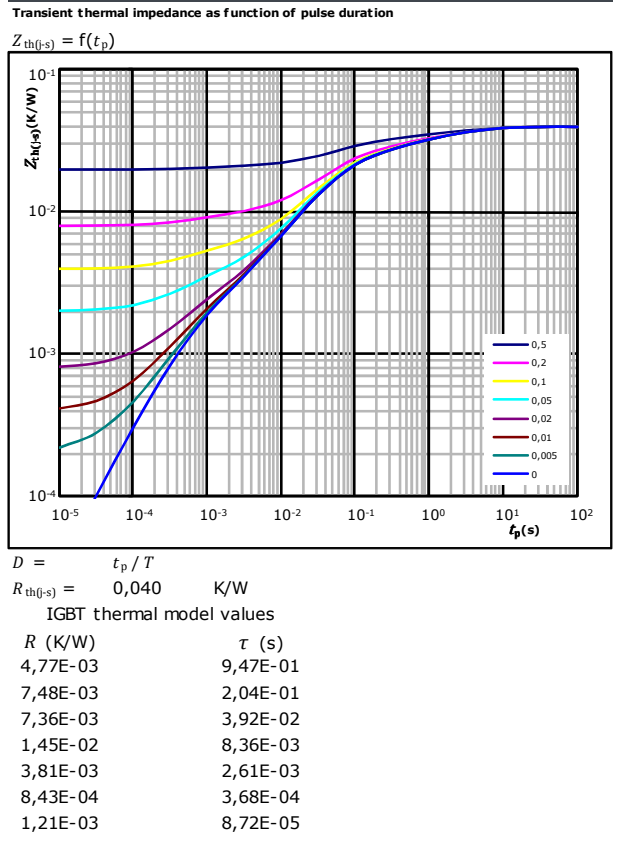


figure 4. IGBT



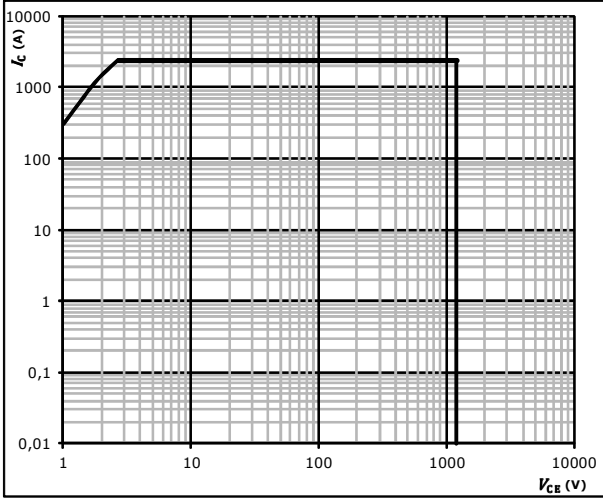


Boost Switch Characteristics

figure 5. IGBT

Safe operating area

$$I_C = f(V_{CE})$$



- $D =$ single pulse
- $T_s =$ 80 °C
- $V_{GE} =$ ±15 V
- $T_j = T_{jmax}$

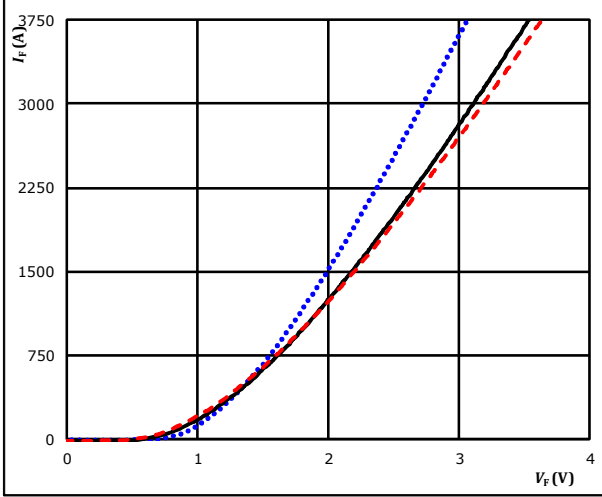


Boost Diode Characteristics

figure 1. FWD

Typical forward characteristics

$$I_F = f(V_F)$$

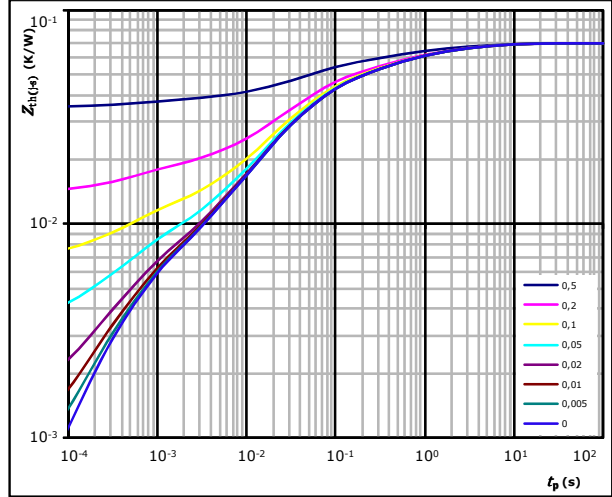


$t_p = 250 \mu s$
 T_j : 25 °C
 125 °C ———
 150 °C - - - -

figure 2. FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 0,07 \text{ K/W}$

FWD thermal model values

R (K/W)	τ (s)
4,91E-03	1,04E+00
1,02E-02	2,14E-01
1,57E-02	4,54E-02
2,42E-02	7,86E-03
8,72E-03	2,17E-03
2,15E-03	3,47E-04
4,02E-03	7,64E-05

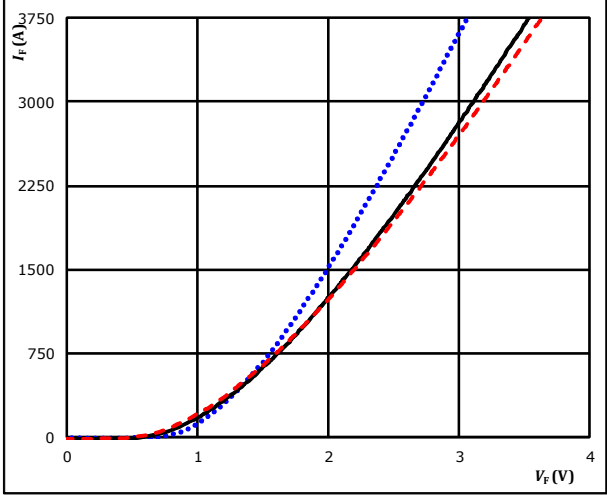


Boost Sw.Inv.Diode Characteristics

figure 1. FWD

Typical forward characteristics

$$I_F = f(V_F)$$

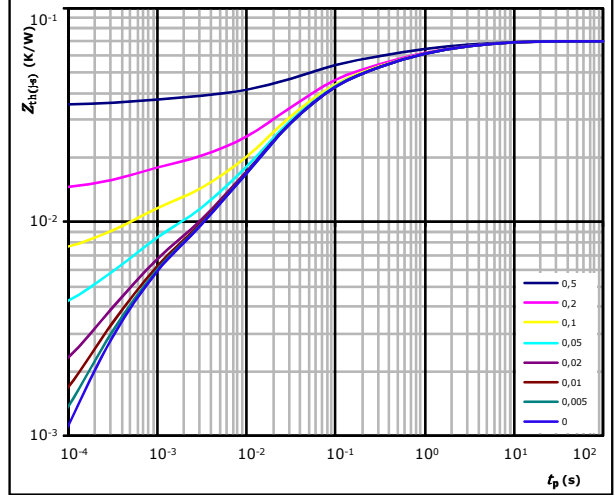


$t_p = 250 \mu s$
 T_j : 25 °C (blue dotted line)
 125 °C (black solid line)
 150 °C (red dashed line)

figure 2. FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 0,07$ K/W

FWD thermal model values

R (K/W)	τ (s)
4,91E-03	1,04E+00
1,02E-02	2,14E-01
1,57E-02	4,54E-02
2,42E-02	7,86E-03
8,72E-03	2,17E-03
2,15E-03	3,47E-04
4,02E-03	7,64E-05

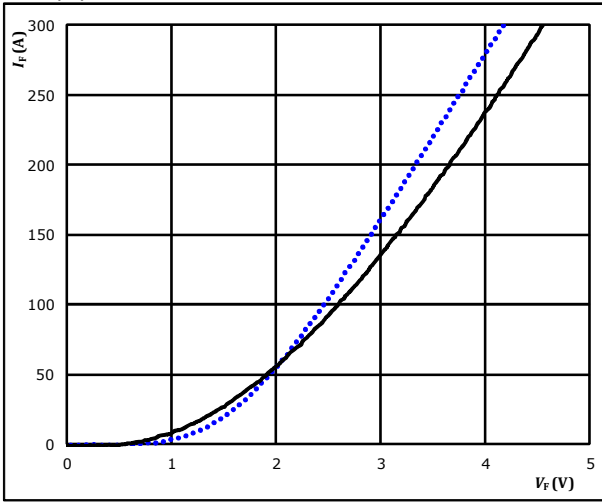


Boost Sw. Protection Diode Characteristics

figure 1. FWD

Typical forward characteristics

$$I_F = f(V_F)$$

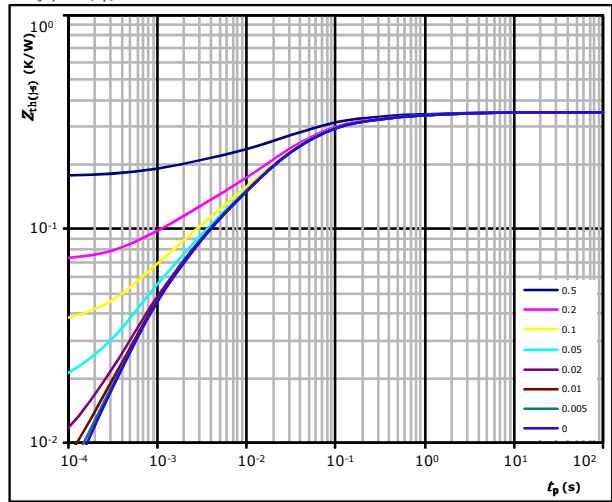


$t_p = 250 \mu s$ $T_j: 25 \text{ }^\circ\text{C}$ (dotted blue line) $125 \text{ }^\circ\text{C}$ (solid black line)

figure 2. FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 0,35 \text{ K/W}$

FWD thermal model values

R (K/W)	τ (s)
1,68E-02	5,53E-01
3,42E-02	7,61E-02
1,32E-01	1,28E-02
9,39E-02	3,66E-03
3,70E-02	9,02E-04
3,86E-02	2,43E-04

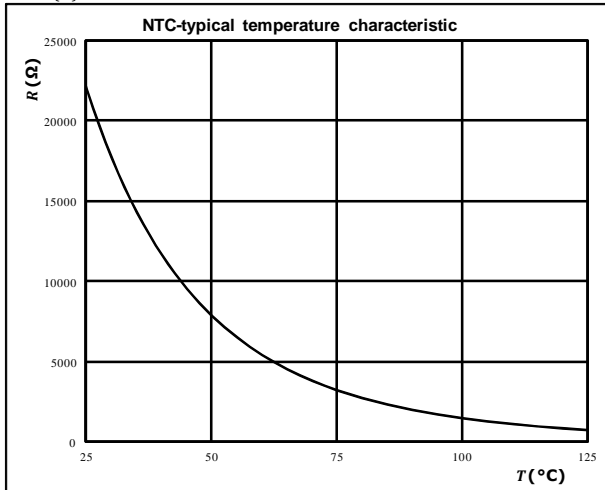


Thermistor Characteristics

figure 1. Thermistor

Typical NTC characteristic
as a function of temperature

$$R = f(T)$$

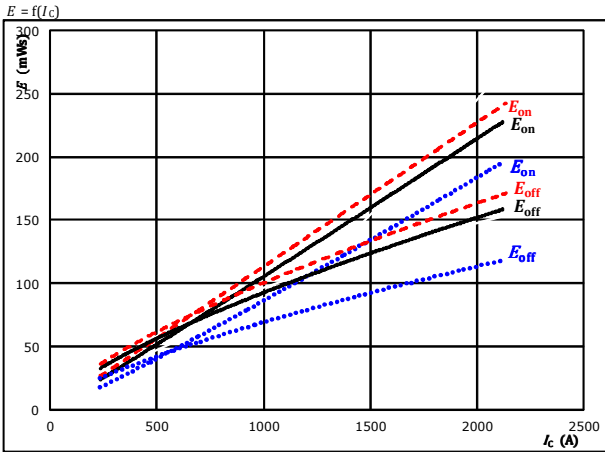




Buck Switching Characteristics

figure 1. IGBT

Typical switching energy losses as a function of collector current

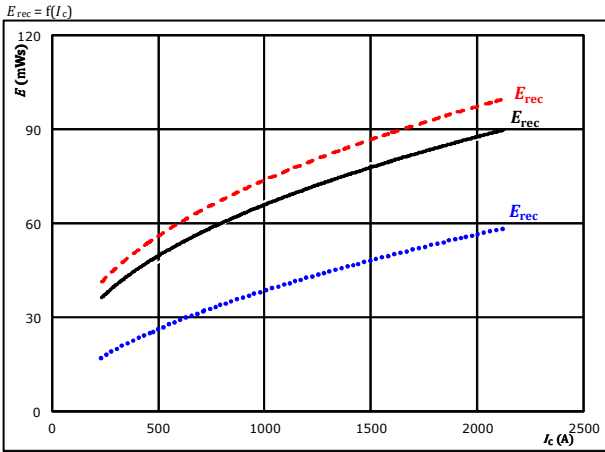


With an inductive load at

$V_{CE} = 600$ V	$T_j: 25$ °C
$V_{GE} = 16/-8$ V	125 °C	————
$R_{gon} = 0,417$ Ω	150 °C	-----
$R_{goff} = 0,417$ Ω		

figure 2. FWD

Typical reverse recovered energy loss as a function of collector current



With an inductive load at

$V_{CE} = 600$ V	$T_j: 25$ °C
$V_{GE} = 16/-8$ V	125 °C	————
$R_{gon} = 0,417$ Ω	150 °C	-----



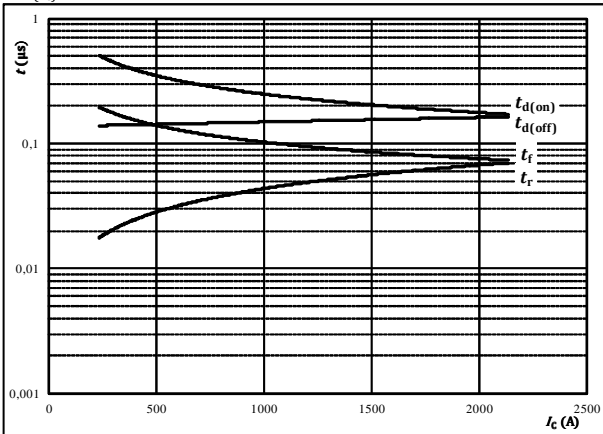
Vincotech

Buck Switching Characteristics

figure 3. IGBT

Typical switching times as a function of collector current

$$t = f(I_c)$$



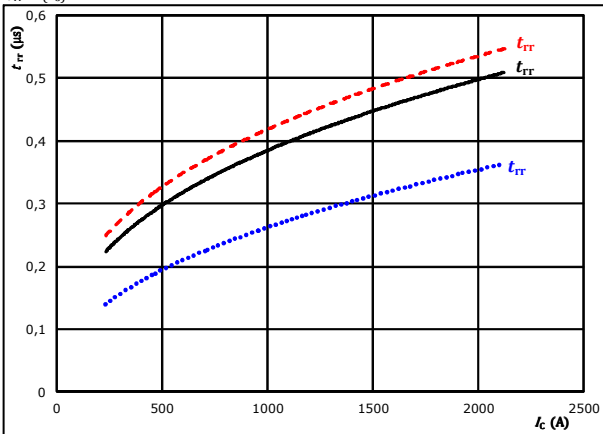
With an inductive load at

$T_j =$	150	$^{\circ}C$
$V_{CE} =$	600	V
$V_{GE} =$	16/-8	V
$R_{gon} =$	0,417	Ω
$R_{goff} =$	0,417	Ω

figure 4. FWD

Typical reverse recovery time as a function of collector current

$$t_{rr} = f(I_c)$$



At	$V_{CE^2} =$	600	V	$T_j =$	25 $^{\circ}C$
	$V_{GE} =$	16/-8	V		125 $^{\circ}C$	————
	$R_{gon} =$	0,417	Ω		150 $^{\circ}C$	-----



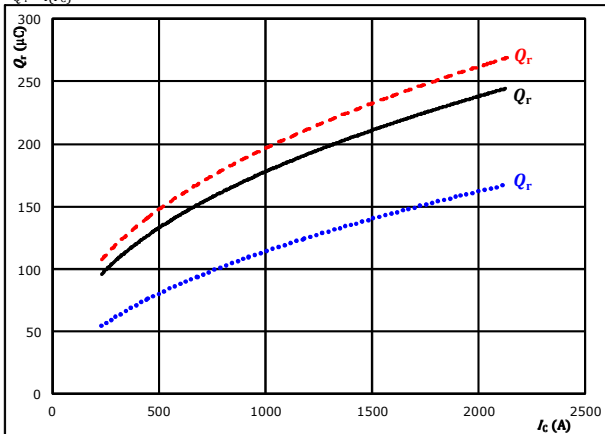
Vincotech

Buck Switching Characteristics

figure 5. FWD

Typical recovered charge as a function of collector current

$$Q_r = f(I_c)$$



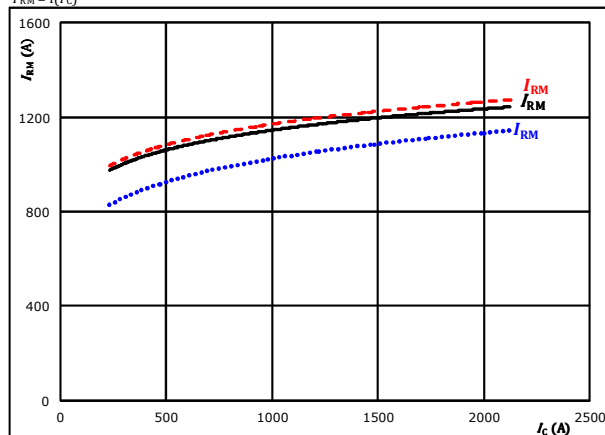
At $V_{CE} = 600$ V
 $V_{GE} = 16/-8$ V
 $R_{gpn} = 0,417$ Ω

T_j : 25 °C (blue dotted line)
 125 °C (black solid line)
 150 °C (red dashed line)

figure 6. FWD

Typical peak reverse recovery current current as a function of collector current

$$I_{RM} = f(I_c)$$



At $V_{CE} = 600$ V
 $V_{GE} = 16/-8$ V
 $R_{gpn} = 0,417$ Ω

T_j : 25 °C (blue dotted line)
 125 °C (black solid line)
 150 °C (red dashed line)



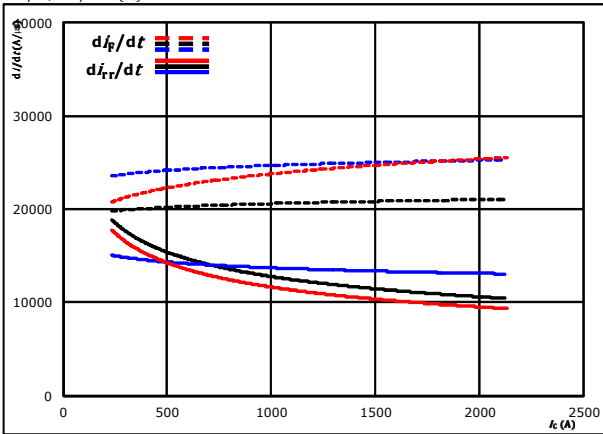
Vincotech

Buck Switching Characteristics

figure 7. FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current

$$di_f/dt, di_{rr}/dt = f(I_C)$$

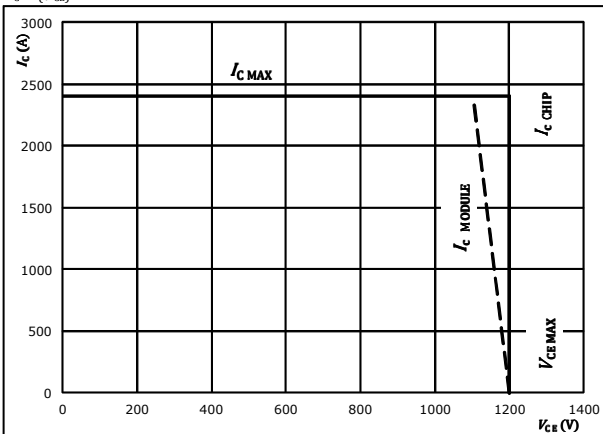


At $V_{CE} = 600$ V $T_j = 25$ °C $\dots\dots\dots$
 $V_{GE} = 16/-8$ V $T_j = 125$ °C ---
 $R_{gpn} = 0,417$ Ω $T_j = 150$ °C - - -

figure 8. IGBT

Reverse bias safe operating area

$$I_C = f(V_{CB})$$



At $T_j = 175$ °C
 $R_{gpn} = 0,417$ Ω
 $R_{goff} = 0,417$ Ω



Buck Switching Definitions

General conditions		
T_j	=	125 °C
R_{gon}	=	0,417 Ω
R_{goff}	=	0,417 Ω

figure 1. IGBT

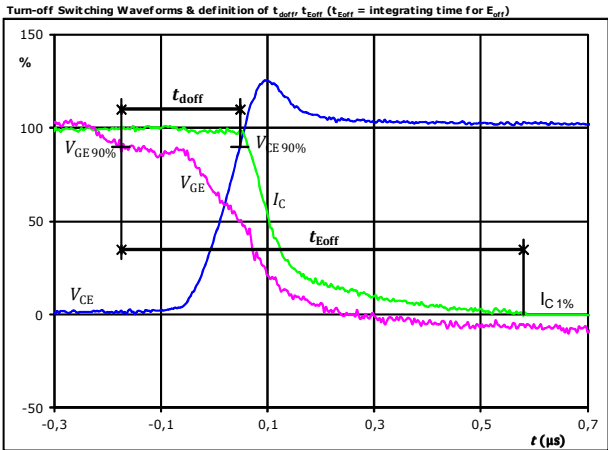


figure 2. IGBT

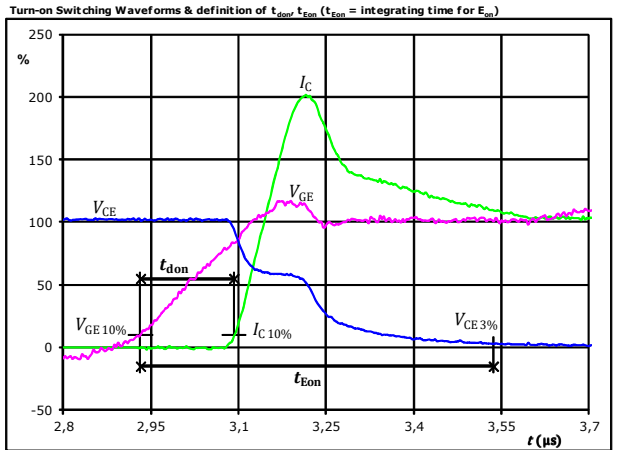


figure 3. IGBT

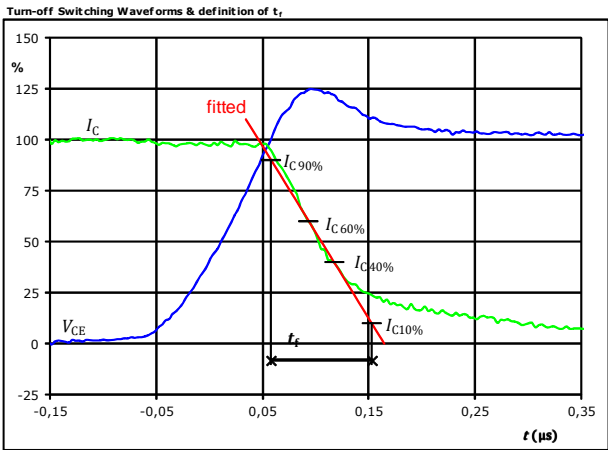
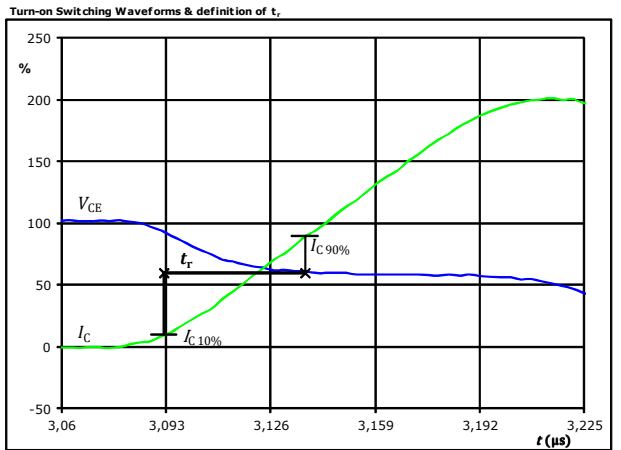


figure 4. IGBT

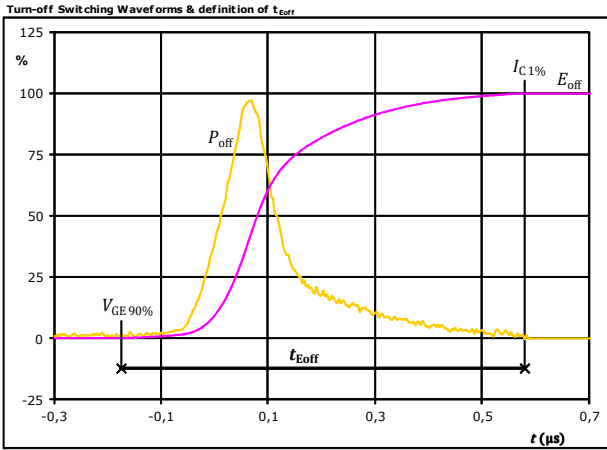




Vincotech

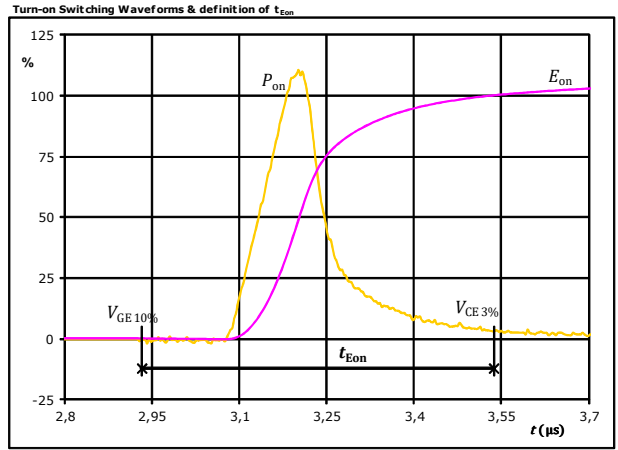
Buck Switching Characteristics

figure 5. IGBT



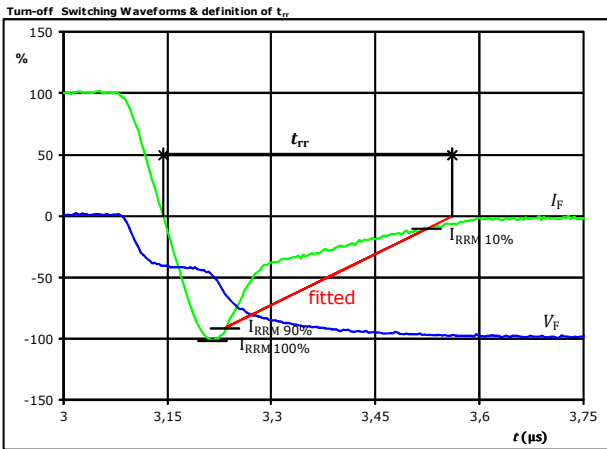
$P_{off}(100\%) = 725,65$ kW
 $E_{off}(100\%) = 108,21$ mJ
 $t_{Eoff} = 0,75$ µs

figure 6. IGBT



$P_{on}(100\%) = 725,65$ kW
 $E_{on}(100\%) = 109,70$ mJ
 $t_{Eon} = 0,60$ µs

figure 7. FWD



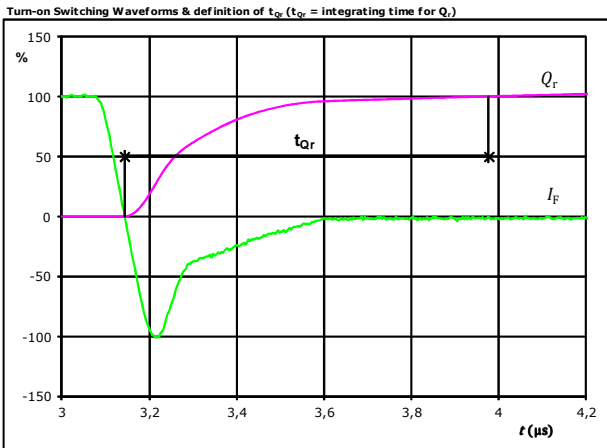
$V_F(100\%) = 600$ V
 $I_F(100\%) = 1209$ A
 $I_{RRM}(100\%) = -1228$ A
 $t_{rr} = 0,408$ µs



Vincotech

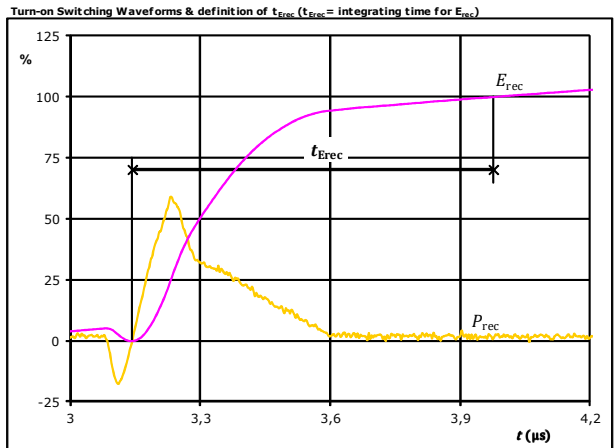
Buck Switching Characteristics

figure 8. FWD



$I_F(100\%) =$	1209	A
$Q_r(100\%) =$	194,17	μC
$t_{Qr} =$	0,83	μs

figure 9. FWD

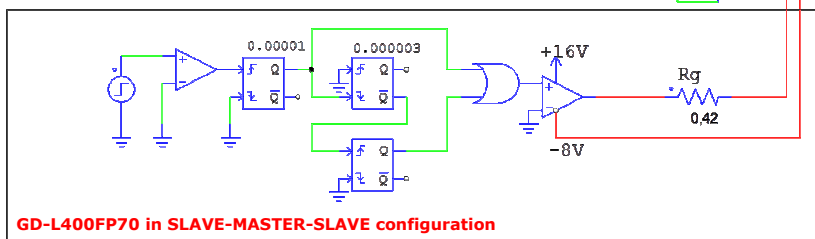
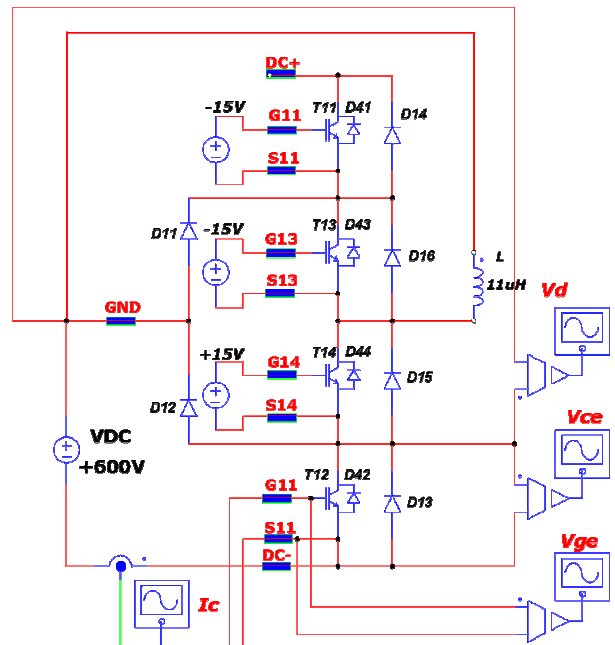


$P_{rec}(100\%) =$	725,65	kW
$E_{rec}(100\%) =$	73,73	mJ
$t_{Erec} =$	0,83	μs

Gate Driver at measurement

For more information see L40x gate driver application note

T12-D12 Switching measurement circuit



GD-L400FP70 in SLAVE-MASTER-SLAVE configuration

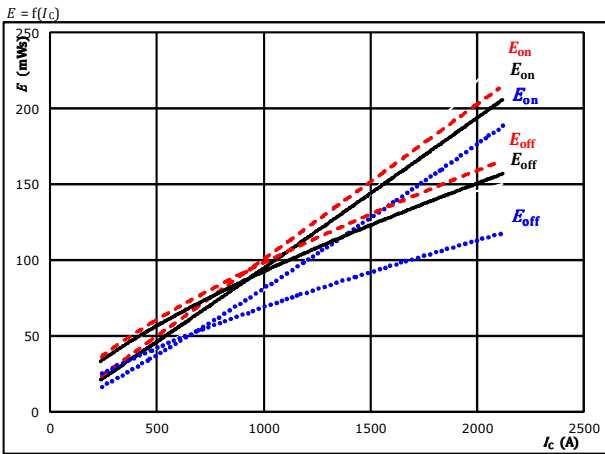


Vincotech

Boost Switching Characteristics

figure 1. IGBT

Typical switching energy losses as a function of collector current



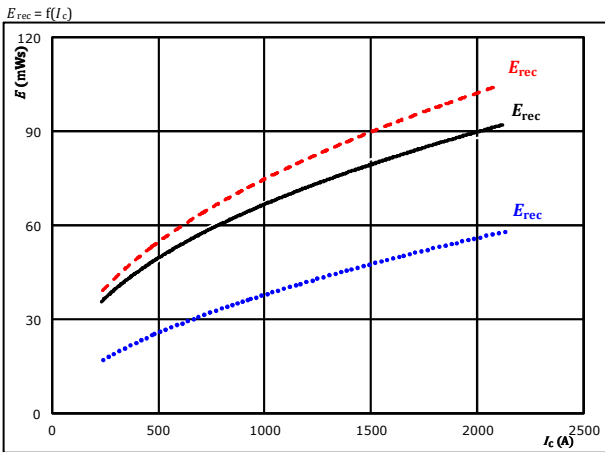
With an inductive load at

$V_{CE} = 600$ V
 $V_{GE} = 16/-8$ V
 $R_{gon} = 0,417$ Ω
 $R_{goff} = 0,417$ Ω

T_j : 25 °C (dotted blue)
 125 °C (solid black)
 150 °C (dashed red)

figure 2. FWD

Typical reverse recovered energy loss as a function of collector current



With an inductive load at

$V_{CE} = 600$ V
 $V_{GE} = 16/-8$ V
 $R_{gon} = 0,417$ Ω

T_j : 25 °C (dotted blue)
 125 °C (solid black)
 150 °C (dashed red)



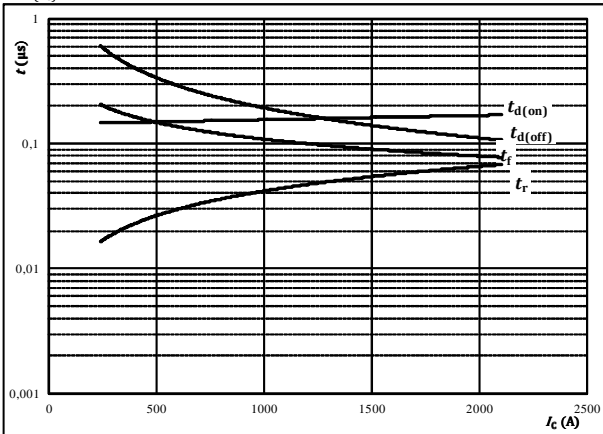
Vincotech

Boost Switching Characteristics

figure 3. IGBT

Typical switching times as a function of collector current

$$t = f(I_c)$$



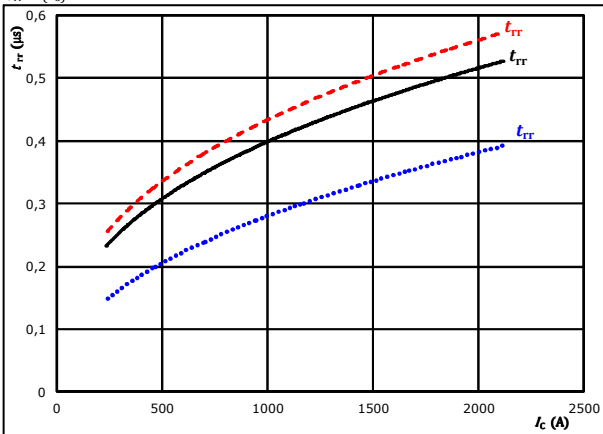
With an inductive load at

$T_j =$	150	°C
$V_{CE} =$	600	V
$V_{GE} =$	16/-8	V
$R_{gon} =$	0,417	Ω
$R_{goff} =$	0,417	Ω

figure 4. FWD

Typical reverse recovery time as a function of collector current

$$t_{rr} = f(I_c)$$



At	$V_{CE} =$	600	V	$T_j =$	25 °C
	$V_{GE} =$	16/-8	V		125 °C	————
	$R_{gon} =$	0,417	Ω		150 °C	- - - -



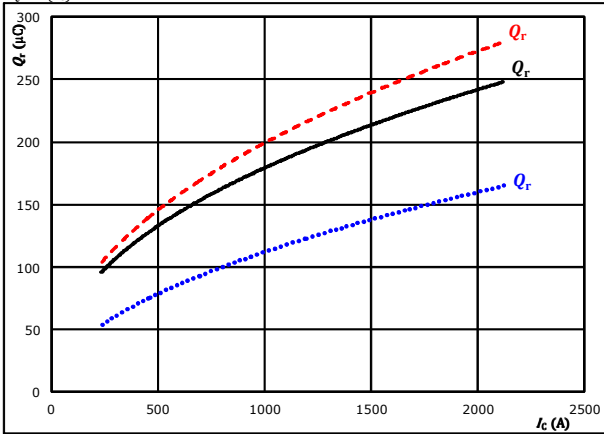
Vincotech

Boost Switching Characteristics

figure 5. FWD

Typical recovered charge as a function of collector current

$$Q_r = f(I_c)$$

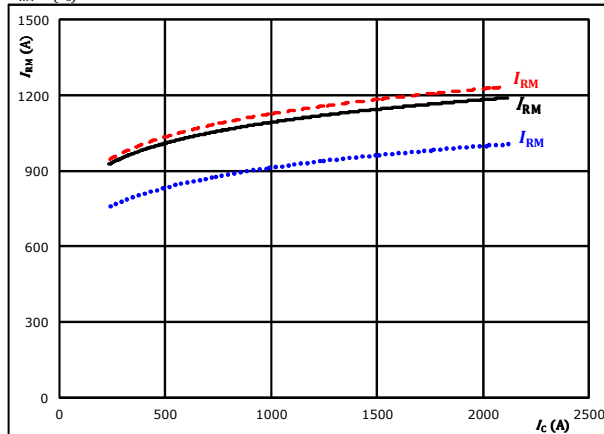


At $V_{CE} = 600$ V $T_j: 25$ °C $\dots\dots\dots$
 $V_{GE} = 16/-8$ V 125 °C ---
 $R_{gpn} = 0,417$ Ω 150 °C ---

figure 6. FWD

Typical peak reverse recovery current current as a function of collector current

$$I_{RM} = f(I_c)$$



At $V_{CE} = 600$ V $T_j: 25$ °C $\dots\dots\dots$
 $V_{GE} = 16/-8$ V 125 °C ---
 $R_{gpn} = 0,417$ Ω 150 °C ---



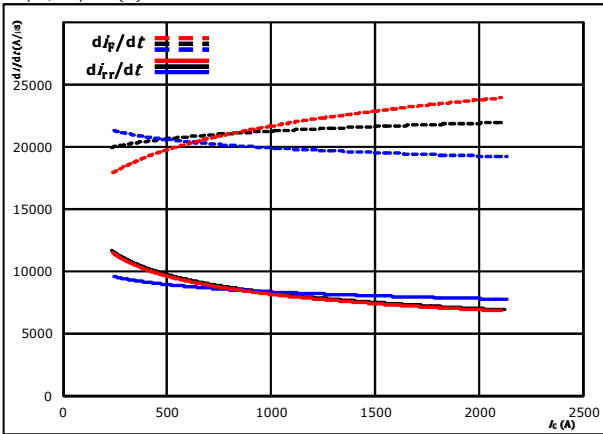
Vincotech

Boost Switching Characteristics

figure 7. FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current

$$di_f/dt, di_{rr}/dt = f(I_c)$$

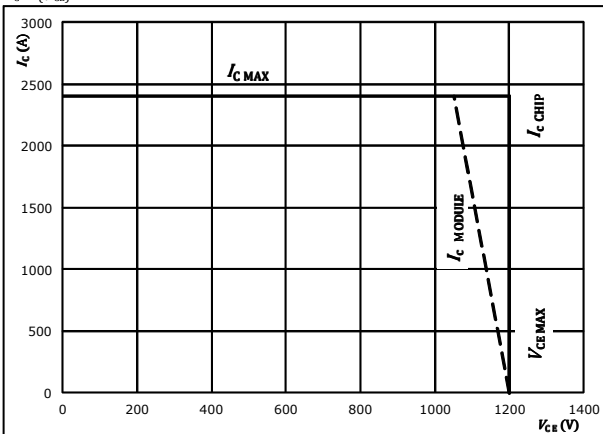


At $V_{CE} = 600$ V $T_j = 25$ °C $\dots\dots\dots$
 $V_{GE} = 16/-8$ V $T_j = 125$ °C —
 $R_{gpn} = 0,417$ Ω $T_j = 150$ °C $-\text{ - - -}$

figure 8. IGBT

Reverse bias safe operating area

$$I_c = f(V_{CE})$$



At $T_j = 175$ °C
 $R_{gpn} = 0,417$ Ω
 $R_{goff} = 0,417$ Ω



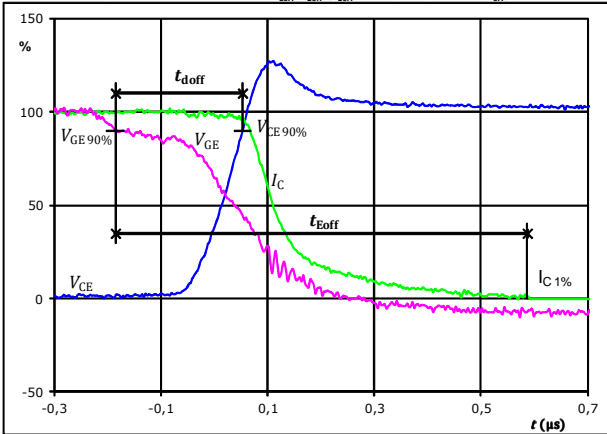
Boost Switching Definitions

General conditions

T_j	=	125 °C
R_{gon}	=	0,417 Ω
R_{goff}	=	0,417 Ω

figure 1. IGBT

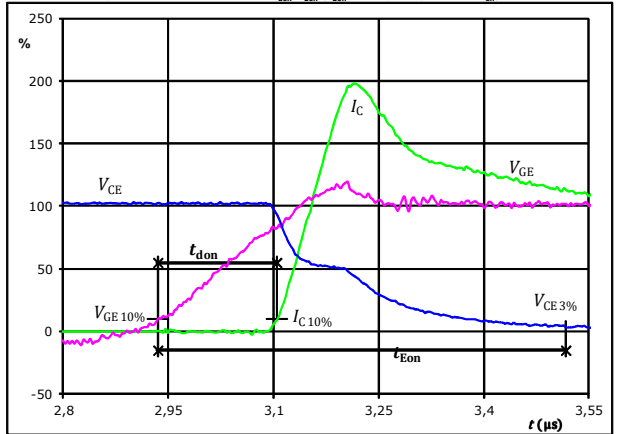
Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff} (t_{Eoff} = integrating time for E_{off})



$V_{CE}(0\%) =$	-8	V
$V_{GE}(100\%) =$	16	V
$V_C(100\%) =$	600	V
$I_C(100\%) =$	1180	A
$t_{doff} =$	0,250	μs
$t_{Eoff} =$	0,772	μs

figure 2. IGBT

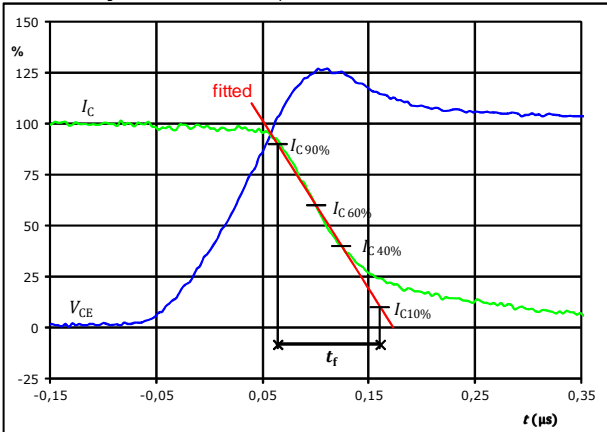
Turn-on Switching Waveforms & definition of t_{don} , t_{Eon} (t_{Eon} = integrating time for E_{on})



$V_{CE}(0\%) =$	-8	V
$V_{GE}(100\%) =$	16	V
$V_C(100\%) =$	600	V
$I_C(100\%) =$	1180	A
$t_{don} =$	0,156	μs
$t_{Eon} =$	0,582	μs

figure 3. IGBT

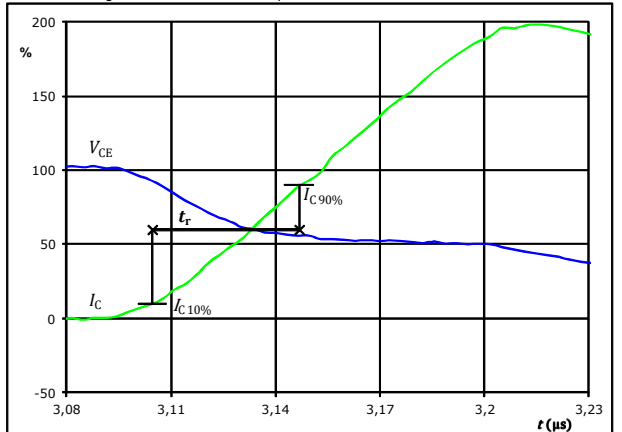
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%) =$	600	V
$I_C(100\%) =$	1180	A
$t_f =$	0,095	μs

figure 4. IGBT

Turn-on Switching Waveforms & definition of t_r



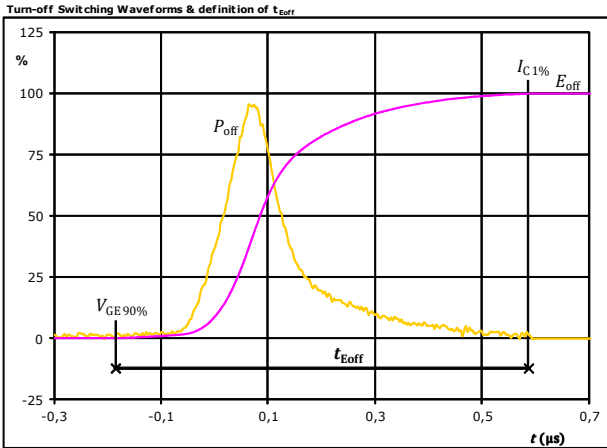
$V_C(100\%) =$	600	V
$I_C(100\%) =$	1180	A
$t_r =$	0,042	μs



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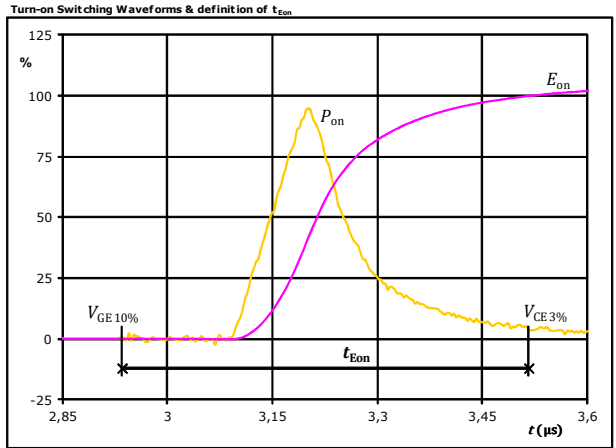
Boost Switching Characteristics

figure 5. IGBT



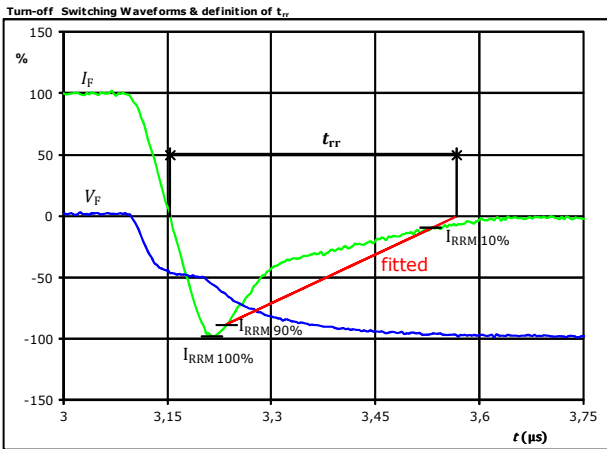
$P_{off}(100\%) =$	707,96	kW
$E_{off}(100\%) =$	107,48	mJ
$t_{Eoff} =$	0,77	μs

figure 6. IGBT



$P_{on}(100\%) =$	707,96	kW
$E_{on}(100\%) =$	97,83	mJ
$t_{Eon} =$	0,58	μs

figure 7. FWD



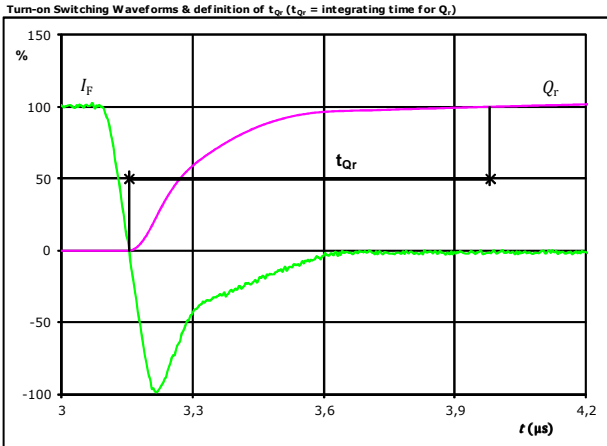
$V_F(100\%) =$	600	V
$I_F(100\%) =$	1180	A
$I_{RRM}(100\%) =$	-1173	A
$t_{rr} =$	0,413	μs



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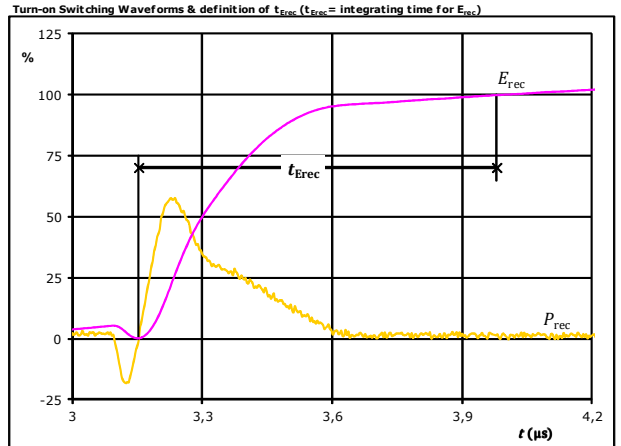
Boost Switching Characteristics

figure 8. FWD



I_F (100%) =	1180	A
Q_r (100%) =	192,45	μC
t_{Qr} =	0,83	μs

figure 9. FWD

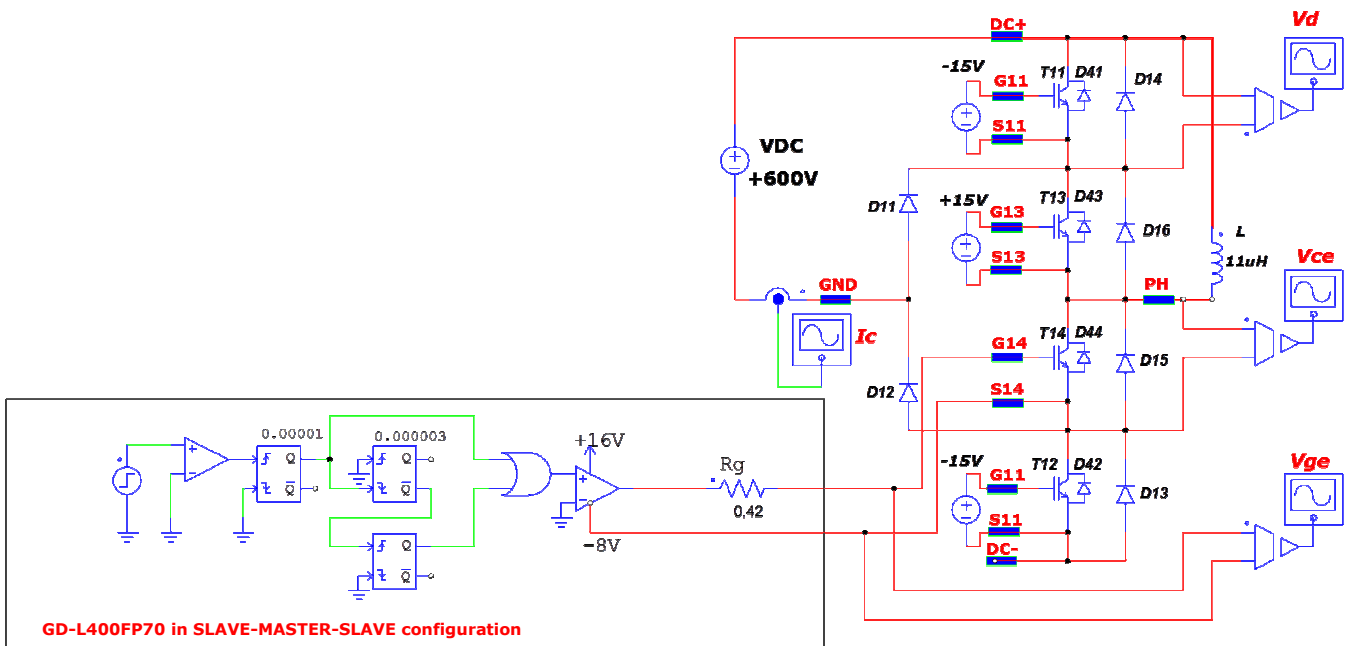


P_{rec} (100%) =	707,96	kW
E_{rec} (100%) =	72,46	mJ
t_{Erec} =	0,83	μs

Gate Driver at measurement

For more information see L40x gate driver application note

T14-D14 Switching measurement circuit








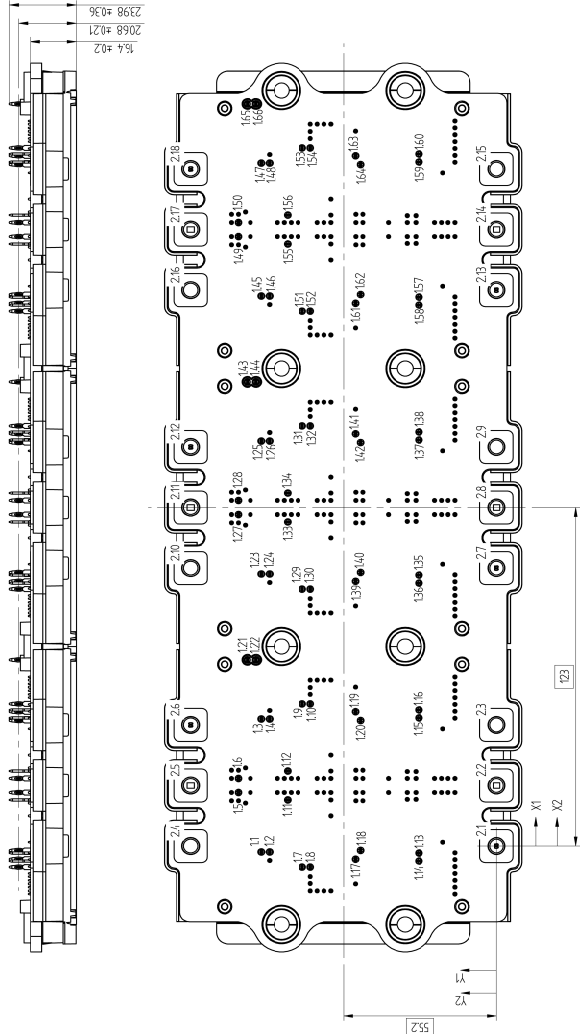
70-W624NIA1K2M702-L400FP70

datasheet

Vincotech

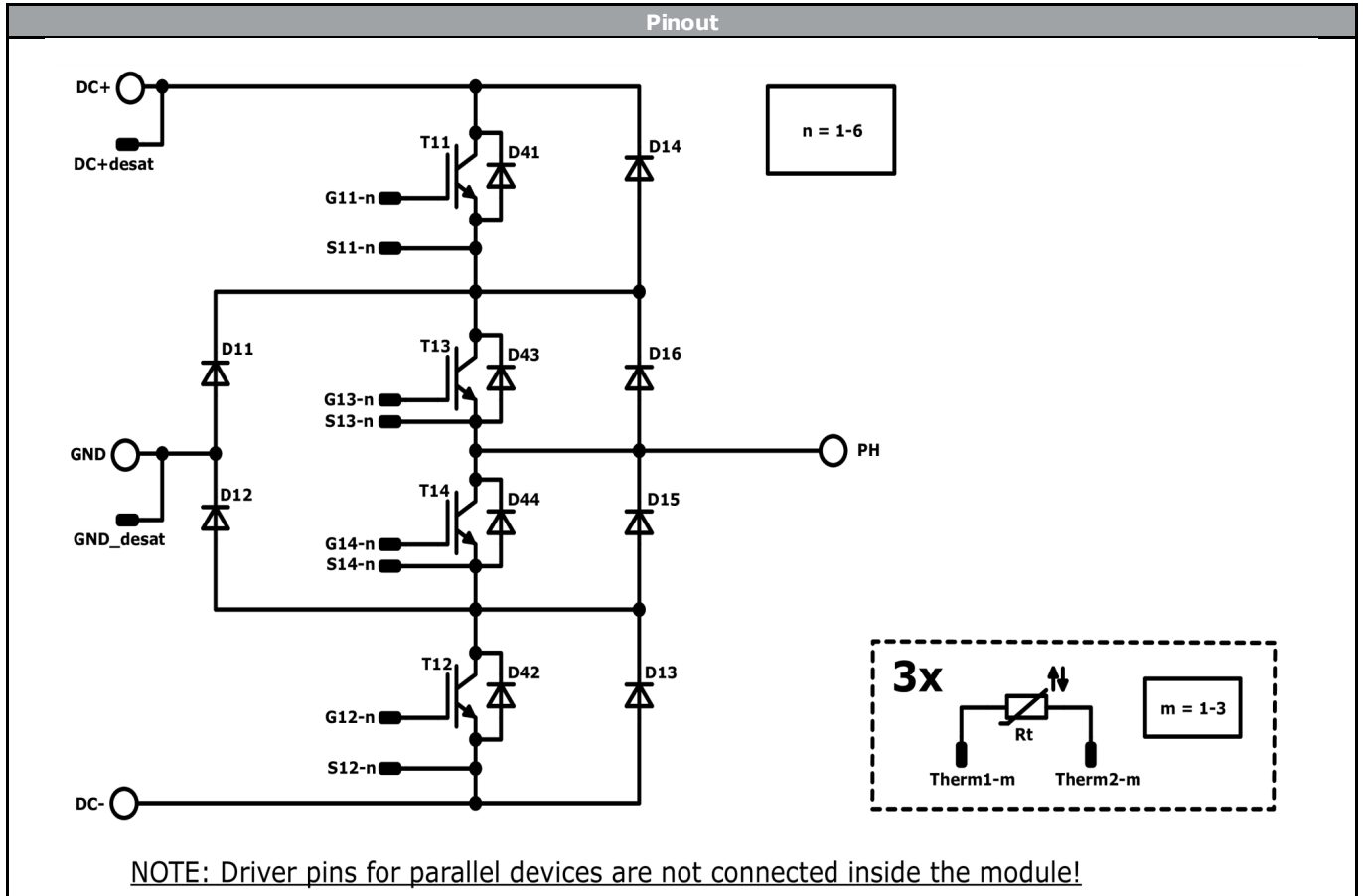
Ordering Code & Marking																															
Version				Ordering Code																											
without thermal paste				70-W624NIA1K2M702-L400FP70																											
<table border="1"> <thead> <tr> <th rowspan="2">Name</th> <th rowspan="2">Text</th> <th>Name</th> <th>Date code</th> <th>UL & VIN</th> <th>Lot</th> <th>Serial</th> </tr> <tr> <td>NN-NNNNNNNNNNNNNN-TTTTTTTV</td> <td>WWYY</td> <td>UL VIN</td> <td>LLLLL</td> <td>SSSS</td> </tr> </thead> <tbody> <tr> <td rowspan="2">  YK/Date code Lot Serial Vincotech UL </td> <td rowspan="2">Datamatrix</td> <td>Type&Ver</td> <td>Lot number</td> <td>Serial</td> <td>Date code</td> <td></td> </tr> <tr> <td>TTTTTTTV</td> <td>LLLLL</td> <td>SSSS</td> <td>WWYY</td> <td></td> <td></td> </tr> </tbody> </table>							Name	Text	Name	Date code	UL & VIN	Lot	Serial	NN-NNNNNNNNNNNNNN-TTTTTTTV	WWYY	UL VIN	LLLLL	SSSS	 YK/Date code Lot Serial Vincotech UL	Datamatrix	Type&Ver	Lot number	Serial	Date code		TTTTTTTV	LLLLL	SSSS	WWYY		
Name	Text	Name	Date code	UL & VIN	Lot	Serial																									
		NN-NNNNNNNNNNNNNN-TTTTTTTV	WWYY	UL VIN	LLLLL	SSSS																									
 YK/Date code Lot Serial Vincotech UL	Datamatrix	Type&Ver	Lot number	Serial	Date code																										
		TTTTTTTV	LLLLL	SSSS	WWYY																										

Outline							
Driver pins				Power connections			
Pin	X1	Y1	Function	M6 screw	X2	Y2	Function
1.1	-2,15	84,85	G11-1	2.1	0	0	PH
1.2	-2,15	81,95	S11-1	2.2	22	0	PH
1.3	46,15	84,85	G11-2	2.3	44	0	PH
1.4	46,15	81,95	S11-2	2.4	0	110,41	DC+
1.5	19,45	93,05	DC+desat	2.5	22	110,41	GND
1.6	24,55	93,05	DC+desat	2.6	44	110,41	DC-
1.7	-7,65	70,05	G13-1	2.7	101	0	PH
1.8	-7,65	67,15	S13-1	2.8	123	0	PH
1.9	51,65	70,05	G13-2	2.9	145	0	PH
1.10	51,65	67,15	S13-2	2.10	101	110,41	DC+
1.11	16,75	75,35	GND desat	2.11	123	110,41	GND
1.12	27,25	75,35	GND desat	2.12	145	110,41	DC-
1.13	-2,55	28	G14-1	2.13	202	0	PH
1.14	-5,45	28	S14-1	2.14	224	0	PH
1.15	46,55	28	G14-2	2.15	246	0	PH
1.16	49,45	28	S14-2	2.16	202	110,41	DC+
1.17	-4,8	50,85	G12-1	2.17	224	110,41	GND
1.18	-1,6	49,05	S12-1	2.18	246	110,41	DC-
1.19	48,8	50,85	G12-2				
1.20	45,6	49,05	S12-2				
1.21	67,65	89,8	Therm1-1				
1.22	67,65	86,7	Therm2-1				
1.23	98,85	84,85	G11-3				
1.24	98,85	81,95	S11-3				
1.25	147,15	84,85	G11-4				
1.26	147,15	81,95	S11-4				
1.27	120,45	93,05	DC+desat				
1.28	125,55	93,05	DC+desat				
1.29	93,35	70,05	G13-3				
1.30	93,35	67,15	S13-3				
1.31	152,65	70,05	G13-4				
1.32	152,65	67,15	S13-4				
1.33	117,75	75,35	GND desat				
1.34	128,25	75,35	GND desat				
1.35	98,45	28	G14-3				
1.36	95,55	28	S14-3				
1.37	147,55	28	G14-4				
1.38	150,45	28	S14-4				
1.39	96,2	50,85	G12-3				
1.40	99,4	49,05	S12-3				
1.41	149,8	50,85	G12-4				
1.42	146,6	49,05	S12-4				
1.43	168,65	89,8	Therm1-2				
1.44	168,65	86,7	Therm2-2				
1.45	199,85	84,85	G11-5				
1.46	199,85	81,95	S11-5				
1.47	248,15	84,85	G11-6				
1.48	248,15	81,95	S11-6				
1.49	221,45	93,05	DC+desat				
1.50	226,55	93,05	DC+desat				
1.51	194,35	70,05	G13-5				
1.52	194,35	67,15	S13-5				
1.53	253,65	70,05	G13-6				
1.54	253,65	67,15	S13-6				
1.55	218,75	75,35	GND desat				
1.56	229,25	75,35	GND desat				
1.57	199,45	28	G14-5				
1.58	196,55	28	S14-5				
1.59	248,55	28	G14-6				
1.60	251,45	28	S14-6				
1.61	197,2	50,85	G12-5				
1.62	200,4	49,05	S12-5				
1.63	250,8	50,85	G12-6				
1.64	247,6	49,05	S12-6				
1.65	269,65	89,8	Therm1-3				
1.66	269,65	86,7	Therm2-3				





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Identification					
ID	Component	Voltage	Current	Function	Comment
T11, T12	IGBT	1200 V	1200 A	Buck Switch	
D11, D12	FWD	1200 V	1200 A	Buck Diode	
D41, D42	FWD	1200 V	90 A	Buck Sw. Protection Diode	
T13, T14	IGBT	1200 V	1200 A	Boost Switch	
D13, D14	FWD	1200 V	1200 A	Boost Diode	
D16, D15	FWD	1200 V	1200 A	Boost Sw.Inv.Diode	
D43, D44	FWD	1200 V	90 A	Boost Sw. Protection Diode	
Rt	Thermistor			Thermistor	




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Packaging instruction			
Standard packaging quantity (SPQ) 4	>SPQ	Standard	<SPQ Sample

Handling instruction
Handling instructions for VINco X12 packages see vincotech.com website.

Package data
Package data for VINco X12 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website. 

Document No.:	Date:	Modification:	Pages
70-W624NIA1K2M702-L400FP70-D3-14	08 July 2021	Pin coordinates corrected	33

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LIFE SUPPORT POLICY

Vincotech products are not authorised for use as critical components in life support devices or systems without the express written approval of Vincotech.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in labelling can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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